

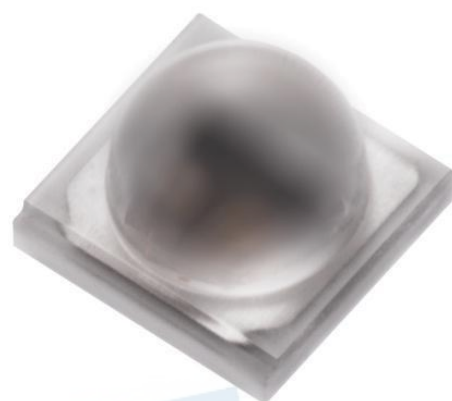
Technical Data Sheet

High Power Infrared LED

HIR-C19D-1N90/L649-P03/TR

Features

- Small package with high efficiency
- Peak wavelength $\lambda_p = 850$ nm
- Soldering methods: SMT
- Thermal resistance (junction to lead): 18K/W.
- Pb free
- Compliance with EU REACH
- Compliance Halogen Free (Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- The product itself will remain within RoHS compliant version.



Description

- HIR-C19D-1N90/L649-P03/TR series is an infrared emitting diode in miniature SMD package which is molded in a water clear silicone with spherical top view lens.
- The device is spectrally matched with silicon photo diode, Phototransistor.

Applications

- CCD Camera
- Infrared applied system

Device Selection Guide

| LED Part No. | Chip Material | Lens Color |
|---------------------------|---------------|-------------|
| HIR-C19D-1N90/L649-P03/TR | GaAlAs | Water clear |

Absolute Maximum Ratings (T_A=25 °C)

| Parameter | Symbol | Rating | Unit |
|--|----------------------|------------|------|
| Continuous Forward Current | I _F | 1500 | mA |
| Peak Forward Current *1 | I _{FP} | 5000 | mA |
| Reverse Voltage | V _R | 5 | V |
| Operating Temperature | T _{opr} | -40 ~ +100 | °C |
| Storage Temperature | T _{stg} | -40 ~ +100 | °C |
| Junction temperature | T _j | 125 | °C |
| Thermal resistance (junction to lead frame) | R _{th(j-L)} | 18 | K/W |
| Power Dissipation @I _F =700mA | P _d | 3 | W |

Notes:

*1. I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%

*2. Note: We suggest that customer should add the heat sink with HIR-C19D-1N90/L649-P03/TR to exclude the heat.

Electro-Optical Characteristics (T_A=25 °C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|----------------------|-------------------|------|------|------|-------|------------------------|
| Total Radiated Power | P _o | -- | 500 | -- | mW | I _F =350 mA |
| | | -- | 900 | -- | | I _F =700 mA |
| | | -- | 1300 | -- | | I _F =1 A |
| Radiant Intensity | I _E | -- | 200 | -- | mW/sr | I _F =350 mA |
| | | -- | 400 | -- | | I _F =700 mA |
| | | -- | 560 | -- | | I _F =1 A |
| Peak Wavelength | λ _P | -- | 850 | -- | nm | I _F =350 mA |
| Spectral Bandwidth | Δλ | -- | 25 | -- | nm | I _F =350 mA |
| Forward Voltage | V _F | -- | 3.0 | -- | V | I _F =350 mA |
| | | -- | 3.3 | -- | | I _F =700 mA |
| | | -- | 3.5 | -- | | I _F =1 A |
| | | -- | 3.8 | -- | | I _F =5 A *3 |
| Reverse Current | I _R | -- | -- | 10 | μA | V _R =5 V |
| View Angle | 2θ _{1/2} | -- | 90 | -- | deg | I _F =20 mA |

Notes:

*3. I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%

Typical Electro-Optical Characteristics Curves

Fig.1
Forward Current vs. Forward Voltage

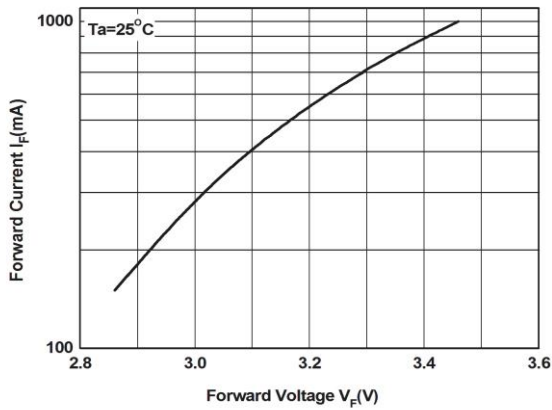


Fig.2
Forward Current vs. Intensity

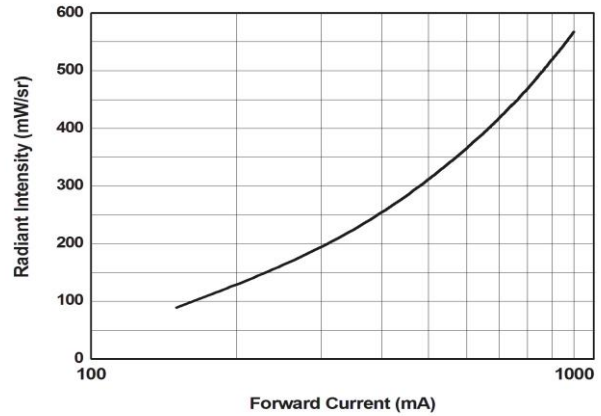


Fig.3
Forward Current vs. Total Power

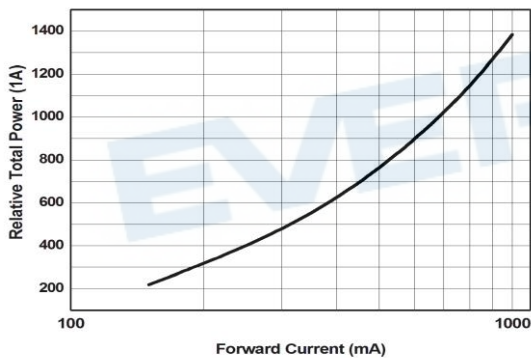


Fig.4
Relative Radiant Intensity vs. Angular Displacement

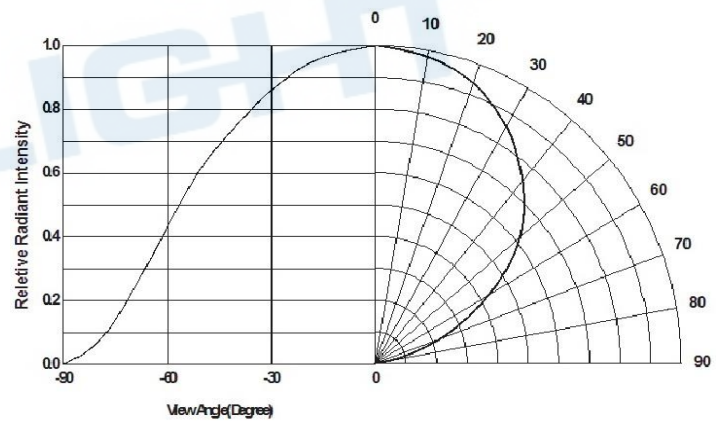
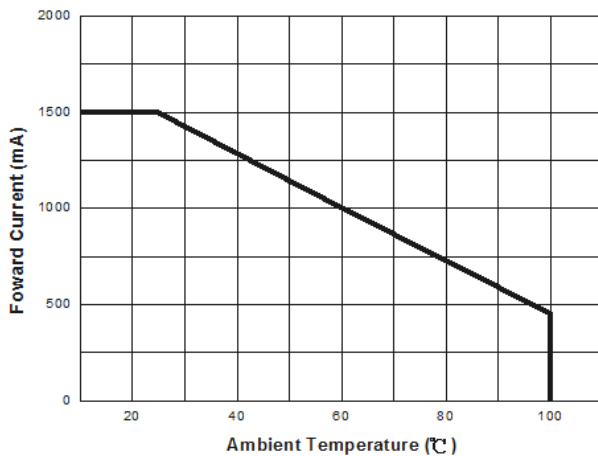


Fig.5
Forward Current vs. Ambient Temperature



Bin Code List

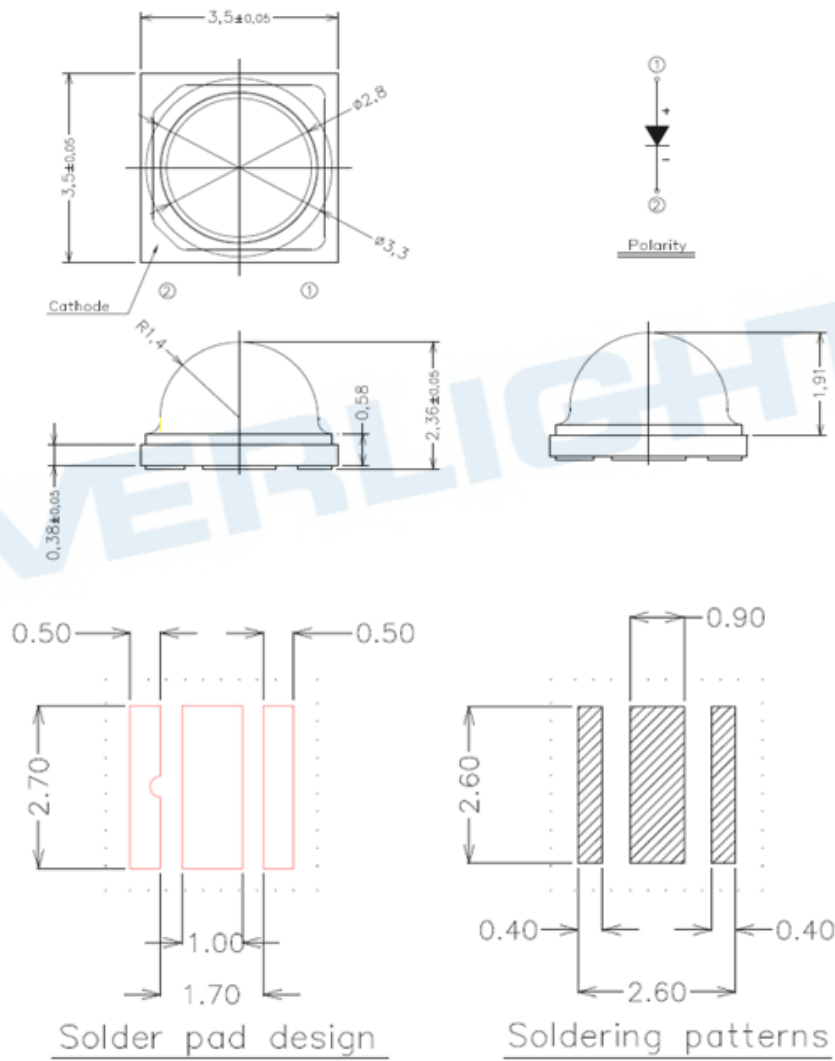
Radiated Power Condition: $I_F=1000\text{mA}$

Unit : mW

| Bin Number | G | H | I |
|------------|------|------|------|
| Min | 800 | 1000 | 1260 |
| Max | 1260 | 1600 | 2000 |

Including test tolerance $\pm 10\%$

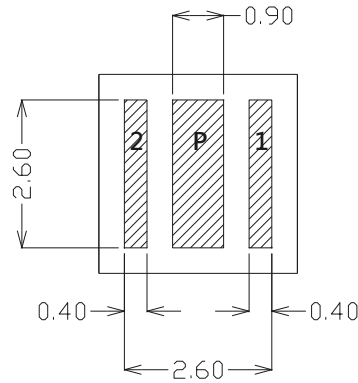
Package Dimension



1. Dimensions are in millimeters.
2. Tolerances unless mentioned are $\pm 0.1\text{mm}$.
3. Do not handle the device by the lens. Incorrect force applied to the lens may lead to the failure of devices.

Pad Configuration

| Pad | 1 | 2 | P |
|----------|-------|---------|-------------|
| Function | Anode | Cathode | Thermal Pad |



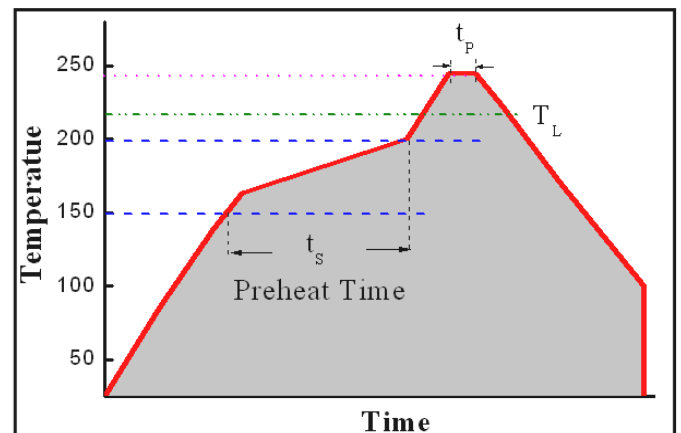
Recommend Soldering patterns

Reflow Soldering Characteristics

For Reflow Process

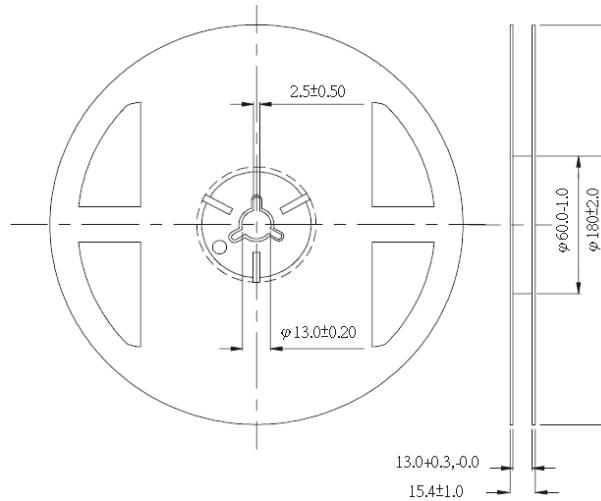
1. C19 series are suitable for SMT processes.
2. Curing of glue in oven must be according to standard operation flow processes.

| Profile Feature | Lead Free Assembly | Unit |
|-----------------------------|--------------------|------|
| Ramp-Up Rate | 2~3 | °C/S |
| Preheat Temperature | 150~200 | °C |
| Preheat Time(t_s) | 60~120 | S |
| Liquid Temperature(T_L) | 217 | °C |
| Time maintained above T_L | 60~90 | S |
| Peak Temperature(T_P) | 240+5 | °C |
| Peak Time (t_p) | Max 20 | S |
| Ramp-Down Rate | 3~5 | °C/S |



3. Reflow soldering should not be done more than twice.
4. In soldering process, stress on the LEDs during heating should be avoided.
5. After soldering, do not bend the circuit board.

Package Dimensions

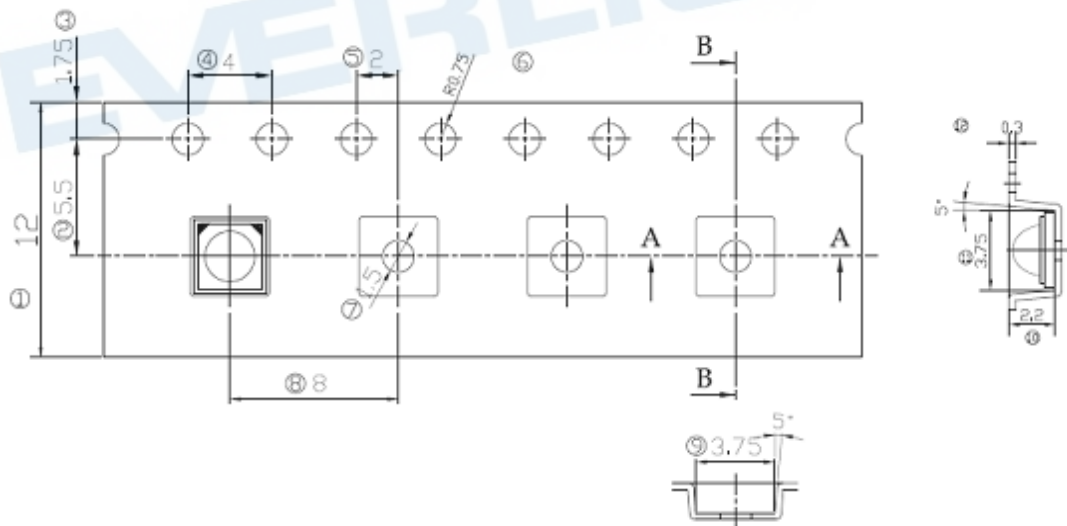


Note:

1. Dimensions are in millimeters
2. The tolerances unless mentioned is ± 0.1 mm

Carrier Tape Dimensions:

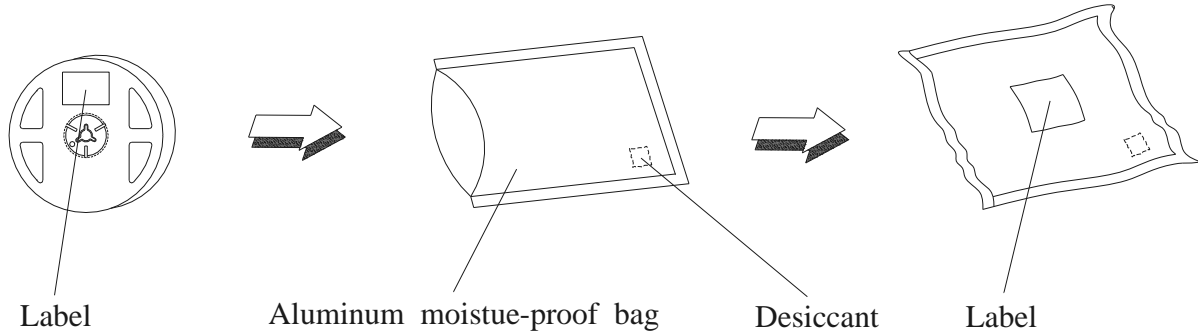
Loaded quantity 400 pcs per reel.



Note:



1. Dimensions are in millimeters
2. The tolerances unless mentioned is ± 0.1 mm

Moisture Resistant Packaging



Moisture Resistant Packing Materials

Label Form Specification

| | |
|--|---|
| RoHS  EVERLIGHT | |
| CPN : XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX | |
| P/N : XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX | |
| LOT NO : XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX | |
| QTY : | HUE : |
| CAT : | REF : |
| REFERENCE : |  |

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number
- X: Month
- Reference: Identify Label Number

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DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Everlight \(亿光\)](#)